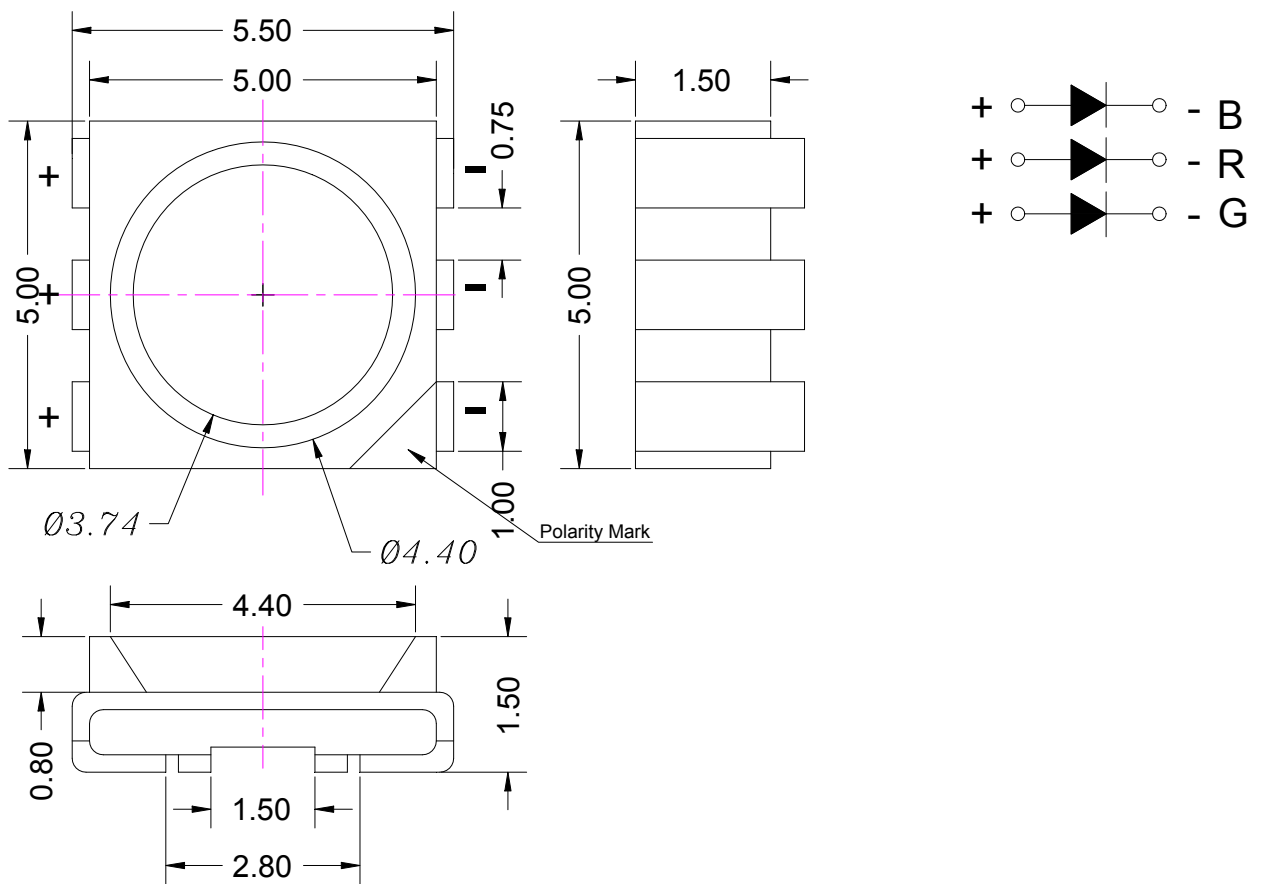




Wen Liu	Fang Yang	Jiang Yang	Fang Wang



Tolerance: $\pm 0.25(0.01)$



Unit mm

Color RGB

Lens-color Water clear

Emitting Material InGaN

Drawing by volitation



3 Characteristic

Forward current	If	30	mA			
Reverse voltage	Vr	5	V			
Power dissipation	Pd	110	mW			
Operating temperature range	Top	-25~+80	°C			
Storage temperature range	Tstg	-30~+80	°C			
Peak pulsing current 1/8 duty f=1KHz	Ifp	125	mA			
Wavelength at peak emission (R)	If=20mA	peak	620	625	630	nm
Wavelength at peak emission (G)			515	520	525	
Wavelength at peak emission (B)			460	465	470	
Spectral half bandwidth	If=20mA			10		
Forward voltage (R)	If=20mA	Vf	1.8	2.0	2.4	V
Forward voltage (G)			3.0	3.3	3.6	
Forward voltage (B)			3.0	3.3	3.6	
Luminous intensity (R)	If=20mA	Iv	800	1000	1200	mcd
Luminous intensity (G)			3000	3500	4000	
Luminous intensity (B)			400	500	600	
Viewing angle at 50% IV	If=10mA		--	120	--	Deg
Reverse current	Vr=5V	Ir	--	--	5	μA



Useful life

Typical Electrical/Optical Characte
(Ta=25° Unless Otherwise Note

If(mA)

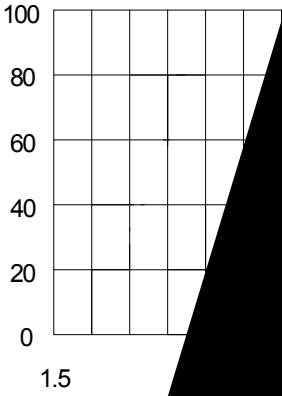


Fig.1 Forward

NOTE

/

2W06 C

2

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f. n@

remb

2

2012 06/15/11 H

i Iron Soldering: the Iron (max 30W) end temperature less than 300 , soldering time \leq 3 seconds, soldering position is minim 2mm from body.

ii Dip Soldering: Max temperature is 260 , time \leq 5, the position is minim 2mm from body.

i Bracket must be bent only if 2mm from colloid.

ii Bracket mould must be finished by fixture or professionals.

iii Bracket mould must be finished ~~before~~ soldering.

iv Bracket mould should assure the consistent between the pin, the distance gap of leads and the circuit board.

i. It should be pay attention to the ordering of all the devices in case of wrong polarity. Devices can't be too close to the heat components, working conditions can't surpass the limits.

ii. It should not assemble LED when the leads are deformed.

iii. When decide to assemble in holes, accurately account the sizes of holes and holes distance of the line base

